Specifications

1. Material
   6061-T6 or equivalent Al core
   Total Thickness: 0.040" (1.016 mm)
   Dielectric Thickness: 0.003"
   Layer 1 - Top Layer, 2 oz copper

2. Hole Plating
   N/A

3. Finish
   A: Electroless Nickel/Immersion Gold (ENIG)

   B: Solder Mask
      Liquid Photo Image (LPI)
      Electro LPI-White
      or Approved Equal
      Solder Mask Over Bare Copper (SMOBC)

   C: Silk Screen
      Black Epoxy Ink, Component Side

4. Tolerances
   Overall board dimension tolerance +/- .010
   Hole diameter >.100 +/- .005
   Hole diameter <=.100 +/- .005